

ABSTRACT OF THE DISCLOSURE

The interior of cavities and through-holes in electrically conductive substrates having high-aspect ratios of 8:1 or greater can be electroplated with a uniform layer of metal on their interior surfaces by using a pulse reverse voltage waveform having a pulse train of long cathodic pulses followed by short anodic pulses even in the absence of conventional additives such as levelers and brighteners.

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